

AMENDMENT

In the Claims:

Please cancel claims 12-32.

Please amend claims 1, 33, and 36 as follows:

1. (Once Amended) A chuck for a plasma processor, said chuck comprising:

- a temperature controlled base;
- a thermal insulator disposed on top of said base;
- a flat support for holding a workpiece, said flat support disposed on top of said thermal insulator, said flat support receiving an incoming heat flux from a plasma during a process; and
- a heater embedded within said flat support,

wherein the heat from said incoming heat flux and said heater is balanced with the cooling from said temperature controlled base such as to control the temperature of said workpiece.

33. (Once Amended) A method for controlling the temperature across a workpiece profile having multiple zones, said method comprising:

- providing a base maintained at a constant temperature, said constant temperature being below the temperature of the workpiece, said base having a thermal insulator mounted on top of said base;
- holding the workpiece against a top face of a workpiece holder, said workpiece holder mounted on top of said thermal insulator;
- applying a heat flux from a plasma during a process to the workpiece; and

heating each zone of the workpiece independently with a heater disposed within
said workpiece holder.

36. (Once Amended) An apparatus for controlling the temperature across a workpiece
profile having multiple zones, said apparatus comprising:

means for maintaining a base at a constant temperature, said constant temperature
being below the temperature of the workpiece, said base having a thermal insulator
mounted on top of said base;

means for holding the workpiece against a top face of a workpiece holder, said
workpiece holder mounted on top of said thermal insulator;

means for applying a heat flux from a plasma during a process to the workpiece;
and

means for independently heating each zone of the workpiece with a heater
disposed within said workpiece holder.

In the Specification:

Please add the following paragraph at page 7, line 15:

-- FIG. 3A is a schematic of the thermal dynamic in the apparatus of FIG. 3 in
accordance with one embodiment of the present invention. --

Please amend the paragraph beginning at page 10, line 5 with the following paragraph:

-- The support 306 may comprise a ceramic or metallic material. The ceramic
may comprise a high temperature non-electrically conductive material, such as for